8. SED1651 Dot Matrix LCD Common Driver

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OVERVIEW

The SED1651 is a 100 output low-power resistance common)row) driver which is suitable for driving a very high capacity dotmatrix LCD panels. It is intended to be used in conjunction with the SED1648 as a pair.

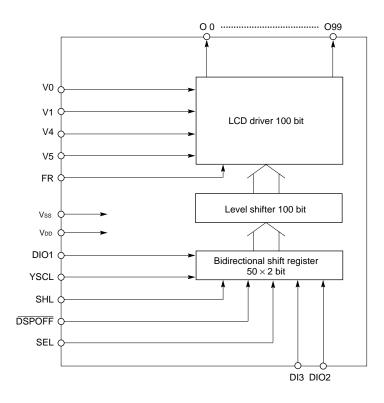
Since the SED1651 is so designed to drive LCD's over a wide range of voltages, and also the maximum potential V₀ of its LCD driving bias voltages is isolated from V_{DD} to allow the LCD driving bias voltages to be externally generated optionally with a high accuracy, it can cope with a wide range of LCD panels.

Owing to its pad layout which can minimize its PC boards mounting space in addition to its selectable bidirectional driver output sequence and as many as 100 LCD output segments of high pressure resistance and low output impedance, it is possible to obtain the highest driver working efficiency for the 1/200 duty panel.

FEATURES

- Number of LCD drive output segments: 100
- Super slim chip configuration
- Common output ON resistance: 750Ω (Typ.)
- Display capacity ... Possible to display 640 × 480 dots.
- Selectable pin output shift direction
- No bias display OFF function
- Adjustable offset bias of LCD power to VDD level
- Wide range of LCD drive voltages: -8 V to -28 V (Absolute maximum rated voltage: -30 V)
- Logic system power supply: -2.7 V to -5.5 V
- Chip packaging SED1651D0A (AL-pad die form)
- No radial rays countermeasure taken in designing

BLOCK DIAGRAM



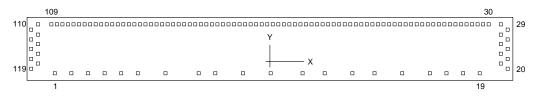
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PIN DESCRIPTION

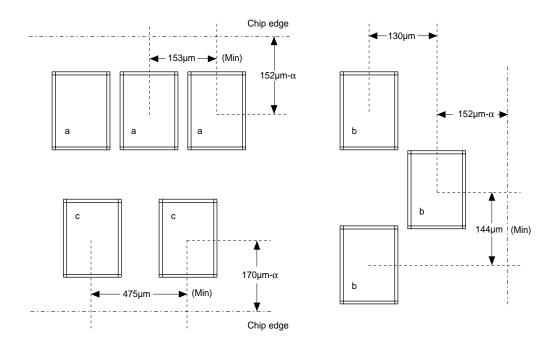
Pin name	I/O		Function					
O0 to O99	0		e common (ro ut changes at	w) output the YSCL falling	g edge.		80	
DIO1 DIO2	I/O	To be se	50×2 bits bidirectional shift register serial data input/output To be set to input or output according to the SHL input The output changes at the YSCL falling edge.					
DI3	I	configura	This is the input pin of scanning pulse in the 50×2 bits configuration. When SEL = L, the DI3 pin to Vss or GND.					
SEL	I		Selection input of bidirectional shift register operating mode H 50 × 2 (DI3 input) L 100					
YSCL	1		Serial data shift clock input The scanning data is shifted at the falling edge.					
		Shift dire	Shift direction selection and DIO pin I/O control input					
		SHL	O output s	hift direction	DIO1	DIO2		
		L	0 → 49	50 → 99	Input	Output		
SHL	I	Н	99 <i>→</i> 50	49 → 0	Ourput	Input	1	
		When SEL = "H", the DI3 input is set to O50 (SHL = "L") or O49 (SHL = "H"). When SEL = "L", the D13 input is ignored and the DIO inputs are shifted continuously.						
DSPOFF	_	When "L	LCD display blanking control input When "L" is input, the content of shift register is cleared and all common outputs become the Vo level instantaneously.					
FR	I	LCD driv	LCD drive output converted signal input					
VDD, VSS	Power supply	Logic po	ver supply	V _{DD} : 0 V (GI	ND) Vss: -	2.7 V to −5.5 \	3	
V0, V1, V4, V5	Power supply	LCD driv	e power suppl	y V ₅ : $-8 \text{ V to} -$ V _{DD} \geq V ₀ \geq V			8	

Respectively Total: 119

PAD LAYOUT AND COORDINATES



1) AL pad specifications (SED1651D0A)



Pad a Opening (X, Y) $110 \times 110 \mu m$ PAD No 30 to 109 Pad b Opening (X, Y) $110 \times 110 \mu m$ PAD No 20 to 29, 110 to 119

Pad c Opening (X, Y) $110 \times 110 \mu m$ PAD No 1 to 19

Unit (µm)

	PAD	Actual dir	mensions		PAD	Actual dir	mensions		PAD	Actual di	mensions
NO.	NAME	X	Y	NO.	NAME	X	Y	NO.	NAME	X	Y
1	DIO2	-5985	-709	43	O23	4078	727	85	O65	-2385	727
2	V0	- 5510		44	O24	3924		86	O66	-2539	
3	V1	-5035		45	O25	3771		87	O67	-2693	
4	V4	-4560		46	O26	3617		88	O68	-2847	
5	V5	-4038		47	O27	3463		89	O69	-3001	
6	Vss	-3164		48	O28	3309		90	O70	-3155	
7	SEL	-2280		49	O29	3155		91	071	-3309	
8	SHL	-1767		50	O30	3001		92	072	-3463	
9	DI3	-1064		51	O31	2847		93	O73	-3617	
10	YSCL	-181		52	O32	2693		94	074	-3771	
11	VDD	770		53	O33	2539		95	O78	-3924	
12	DSPOFF	1283		54	O34	2385		96	O76	-4078	
13	FR	2176		55	O35	2232		97	077	-4232	
14	Vss	2879		56	O36	2078		98	O78	-4386	
15	V5	3753		57	O37	1924		99	079	-4540	
16	V4	4560		58	O38	1770		100	O80	-4694	
17	V1	5035		59	O39	1616		101	O81	-4848	
18	V0	5510		60	O40	1462		102	O82	-5002	
19	DIO1	5985		61	O41	1308		103	O83	-5156	
20	00	6560	_610	62	042	1154		104	O84	-5310	
21	01	6430	-466	63	O43	1000		105	O85	-5463	
22	02	6560	-321	64	044	846		106	O86	-5617	
23	O3	6430	-177	65	045	693		107	O87	-5771	
24	04	6560	-32	66	O46	539		108	O88	-5925	
25	O5	6430	112	67	047	385		109	O89	-6079	
26	O6	6560	257	68	O48	231		110	O90	-6430	690
27	07	6430	401	69	O49	77		111	O91	-6560	545
28	O8	6560	545	70	O50	-77		112	O92	-6430	401
29	O9	6430	690	71	O51	-231		113	O93	-6560	257
30	O10	6079	727	72	O52	-385		114	O94	-6430	112
31	011	5925		73	O53	-539		115	O95	-6560	-32
32	012	5771		74	O54	-693		116	O96	-6430	-177
33	O13	5617		75	O55	-846		117	O97	-6560	-321
34	014	5463		76	O55	-1000		118	O98	-6430	-466
35	O15	5310		77	O57	-1154		119	O99	-6560	-610
36	O16	5156		78	O58	-1308					
37	O17	5002		79	O59	-1462					
38	O18	4848		80	O60	-1616					
39	O19	4694		81	O61	-1770					
40	O20	4540		82	O62	-1924					
41	O21	4386		83	O63	-2078					
42	O22	4232		84	064	-2232					

FUNCTIONAL DESCRIPTION

Shift register

This is a bidirectional shift register to transfer common data.

Being a 50×2 bits configuration, this register can select 50×2 bits or 100 bits according to the status of SEL.

When the 50×2 bits configuration is selected, the input of the 50-bit shift register becomes D13.

Level shifter

This is a level interface circuit used to convert the signal voltage level from the logic system level to LCD drive level.

LCD driver

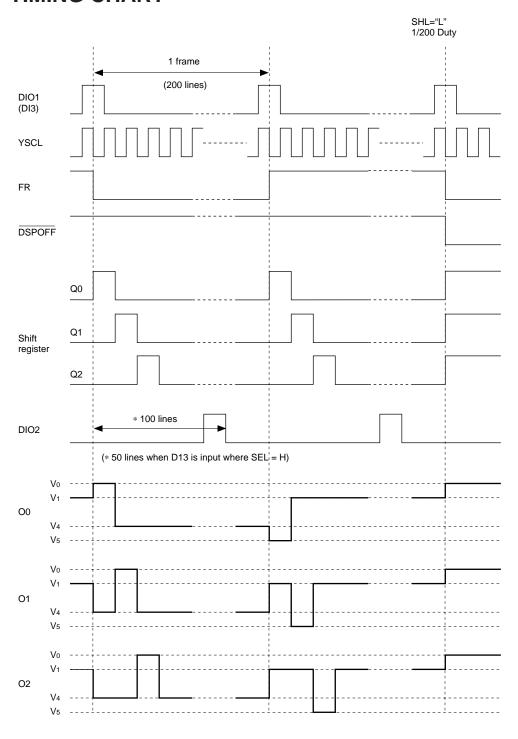
This driver outputs the LCD drive voltage.

The relationship among the display blanking signal DSPOFF, contents of shift register, AC converted signal FR and On output voltage is as shown in the table below:

DSPOFF	Content of shift register	FR	O output voltage			
	Н	Н	V5	(Select level)		
н	П	11	L	Vo	(Select level)	
		Н	V1	(Non-select		
	L	L	V4	level)		
L	_	_	Vo	_		

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TIMING CHART



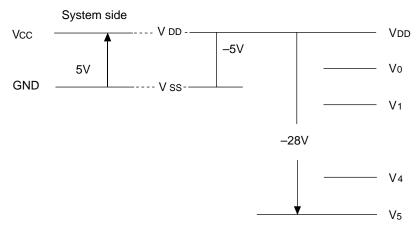
ABSOLUTE MAXIMUM RATINGS

VDD=0V

Parameter	Symbol	Rating	Unit
Supply voltage (1)	Vss	-7.0 to +0.3	V
Supply voltage (2)	V ₅	-30.0 to +0.3	V
Supply voltage (3)	V0, V1, V4	V5-0.3 to +0.3	V
Input voltage	Vı	Vss-0.3 to +0.3	V
Output voltage	Vo	Vss-0.3 to +0.3	V
Output current (1)	lo	20	mA
Output current (2)	Іосом	20	mA
Operating temperature	Topr	-40 to + 85	°C
Storing temperature 1	Tstg 1	-65 to +150	°C

Notes*

1. The voltage of V0, V1, V4 and V5 must always satisfy the condition of VDD \geq V0 \geq V1 \geq V4 \geq V5.



2. Floating of the logic system power during while the LCD drive system power is applied, or exceeding Vss = -2.6 V or less can cause permanent damage to the LSI. Functional operation under these conditions is not implied.

Care should be taken to the power supply sequence especially in the system power ON or OFF.

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ELECTRICAL CHARACTERISTICS

DC characteristics

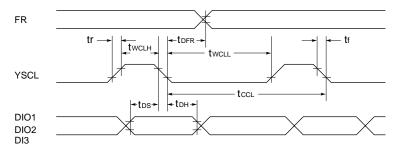
Unless otherwise specified, VDD = V0 = 0V, VSS = -5.5V - 2.7V, Ta = -40 to $85^{\circ}C$.

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	Applicable pin
Supply voltage (1)	Vss	-	-5.5	-5.0	-2.7	V	Vss
Recommended operating voltage	V5	-	-28.0	-	-12.0	V	V ₅
Operation enable voltage	V5	Functional operation	-	-	-8.0	V	V ₅
Supply voltage (2)	Vo	_	2.5	-	0	V	V ₀
Supply voltage (3)	V ₁	_	2/9·V ₅	_	Vdd	V	V ₁
Supply voltage (4)	V4	_	V ₅	_	7/9·V ₅	V	V4
"H" input voltage	VIH	-	0.2·Vss	-	-	V	DIO1, DIO2, FR, YSCL, SHL, DI3
"L" input voltage	VIL	-	_	-	0.8·Vss	V	DSPOFF, SEL
"H" output voltage	Vон	Iон=-0.3mA	VDD-0.4	ı	-	V	DIO1, DIO2
"L" output voltage	Vol	IoL=0.3mA	-	-	Vss+0.4	V	5101, 5102
Input leakage current	Iц	Vss ≤ Vin ≤ 0V	_	-	2.0	μΑ	YSCL, SHL, DI3 DSPOFF, FR, SEL
Input/output leakage current	Ili/O	Vss ≤ Vin ≤ 0V	-	-	5.0	μΑ	DIO1, DIO2
Static current	IDDS	V ₅ =-12.0 ~ -28.0V V _{IH} =V _{DD} , V _{IL} =V _{SS}	-	-	25	μΑ	VDD
Output resistance	Rсом	∆Von=0.5V Vo=Vdd, V1=−1.5V V4=−18.5V V5=−20.0V	-	0.75	1.0	ΚΩ	O0~O99
Average operating current consumption (1)	Iss1	Vss=–5.0V, ViH=VDD ViL=Vss, fyscL=12KHz Frame frequency=60Hz Input data: 1/200 Ta=25°C ?	-	7	15	μΑ	Vss
		Vss= -3.0 V Other conditions are the same as Vss = -5.0 V	_	5	10		
Average operating current consumption (2)	Iss2	Vss=–5.0V, V0=0V, V1=1.5V, V4=18.5V, VEE=V5=–20.0V Other conditions are the same as in the item of ISS 1.	-	7	15	μΑ	V5
Input pin capacitance	Сі	Ta=25°C	_	_	8	pF	YSCL, SHL, DSPOFF, FR, DI3, SEL
Input/output pin capacitance	Ci/o		_	-	15	pF	DIO1, DIO2

AC CHARACTERISTICS

Input timing characteristics

 $V_{IH}=0.2 \times V_{SS}$ $V_{IL}=0.8 \times V_{SS}$



Vss=-5.0V±0.5V, Ta=-40 to 85°C

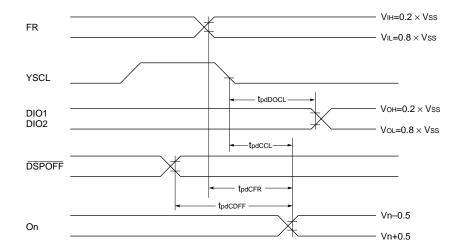
Parameter	Symbol	Condition	Min.	Max.	Unit
Input signal rise time	tr	_	-	50	ns
Input signal fall time	t f	_	_	50	ns
YSCL period	tccl	_	500	_	ns
YSCL "H" pulsewidth	twclh	_	70	_	ns
YSCL "L" pulsewidth	twcll	_	330	_	ns
Data setup time	tos	_	100	_	ns
Data hold time	tdH	_	10	_	ns
Allowable FR delay time	tDFR	_	-300	300	ns

Vss=-5.0V±0.5V, Ta=-40 to 85°C

Parameter	Symbol	Condition	Min.	Max.	Unit
Input signal rise time	tr	_	_	50	ns
Input signal fall time	t f	_	_	50	ns
YSCL period	tccl	_	1000	_	ns
YSCL "H" pulsewidth	twclh	_	160	_	ns
YSCL "L" pulsewidth	twcll	_	330	_	ns
Data setup time	tDS	_	200	_	ns
Data hold time	tDH	_	10	_	ns
Allowable FR delay time	tdfr	_	-500	500	ns

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Output timing characteristics



Vss=-5.0±10%, Ta=-40 to +85°C

Parament	Symbol	Condition	Min.	Max.	Unit
(YSCL - fall to DIO) delay time	tpdDOCL	C _L =15pF	_	350	ns
(YSCL - fall to On output) delay time	tpdccL	V ₅ =-12.0 to		1.0	116
(DSPOFF to On output) delay time	tpdcDOFF	-28.0V	_	1.0	μs
(FR to On Output) delay time	tpdcfr	CL=100pF	_	1.0	μs

Vss=-4.5-2.7V, Ta=-40 to +85°C

Parament	Symbol	Condition	Min.	Max.	Unit
(YSCL - fall to DIO) delay time	tpdDOCL	C _L =15pF	_	400	ns
(YSCL - fall to On output) delay time	tpdccL	V5=-12.0 to	_	2.0	116
(DSPOFF to On output) delay time	tpdcDOFF	–28.0V	_	2.0	μs
(FR to On Output) delay time	tpdcfr	CL=100pF	_	2.0	μs

LCD DRIVE POWER

Each voltage level forming method

To obtain each voltage level for LCD driving, it is optimum to divide the resistance of potential between VDDH and GND to drive the LCD using the voltage follower with an operational amplifier. In taking into consideration of such a case using the operational amplifier, the maximum potential level V0 for LCD driving has been made a separate pin from VDD.

When no operational amplifier is used in V_0 , set $V_0 = V_{DD}$.

When a resistive divider is used, set it to a resistance value as low as possible in the system power capacity.

When a series resistance exists in the power supply line of VDD, a voltage drop of VDD occurs at the LSI power supply pin, the relationship with the LCD's intermediate potential (VDD \geq V0 \geq V1 \geq V4 \geq V5) cannot be met, this causing the LSI to be broken down in some cases. When a protection resistor is inserted, it is necessary to stabilize the voltage by capacitance.

Note in power ON/OFF

Since this LSI is high in the voltage of LCD driving system, when a high voltage is applied to the LCD driving system with the logic system power supply kept floating or above Vss = -2.5 V, an overcurrent flows and LSI breaks down in some cases.

To avoid this, it is recommended to suppress the potential of LCD drive output to V₀ level using the display off function (\overline{DSPOFF}) until the LCD driving system voltage is stabilized.

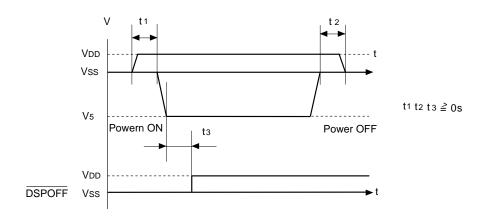
Be sure to follow the power ON/OFF sequence as shown below:

At power ON ... Logic system ON \rightarrow LCD driving system ON or simultaneous ON of the both

At power OFF ... LCD driving system OFF → Logic system OFF or simultaneous OFF of the both

For a countermeasure to such overcurrent, it is effective to put a high-speed melting fuse or protection resistor in series with the LCD power unit.

It is then required to select the optimum value in the protection resistance according to the capacitance of LC cell.



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TYPICAL CIRCUIT DIAGRAM

Configuration Drawing of Large Screen LCD

